

## **Amendments to the Specification**

Please make the following amendments (underlining for added matter and ~~strikethroughs~~ or [[brackets]] for deleted matter) to the specification:

In the “Detailed Description” on page 19 at lines 11-26, please enter the following replacement paragraph:

In addition, during a continuous stamping process, the stamp itself must be re-inked. This may be accomplished by a variety of techniques. Of course, the substrate material may be removed from the apparatus, for example, by cutting the substrate material between the processed and unprocessed portions and inking the stamp as described above. In another embodiment, an inker having an exterior diameter greater than the substrate but less than the interior diameter of the modulated stamp (or vice versa, depending on whether an interior or an exterior surface of the surface is being stamped) may be passed into the apparatus. The surface of the inker opposed to the substrate is fabricated from a “leak proof” material to prevent ink from contacting the substrate. The stamp is allowed to contact the inker and is then modulated so that the inker may be removed. For applications where a substrate is stamped several times, or where it is undesirable to cut sections of the substrate following stamping, the inker 71 (Figure 6A) may be formed in two sections which fit around the substrate 16 for insertion into the stamp 10 (Figure 6 Figures 6B and 6C). In another embodiment, an inking segment 72 may be incorporated into the substrate or wrapped around it. As the substrate is advanced, the stamp will alternately stamp the substrate and be re-inked (Figure 7).